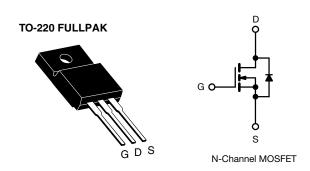
Vishay Siliconix

D Series Power MOSFET



| PRODUCT SUMMARY | | | |
|--|------------------------|-----|--|
| V _{DS} (V) at T _J max. | 450 |) | |
| R _{DS(on)} max. (Ω) at 25 °C | V _{GS} = 10 V | 0.6 | |
| Q _g max. (nC) | 30 | | |
| Q _{gs} (nC) | 4 | | |
| Q _{gd} (nC) | 7 | | |
| Configuration | Sing | le | |

FEATURES

- Optimal design
 - Low area specific on-resistance
 - Low input capacitance (Ciss)
 - Reduced capacitive switching losses
 - High body diode ruggedness
 - Avalanche energy rated (UIS)
- · Optimal efficiency and operation
 - Low cost
 - Simple gate drive circuitry
 - Low figure-of-merit (FOM): Ron x Qa
 - Fast switching
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

APPLICATIONS

- Consumer electronics
 - Displays (LCD or plasma TV)
- Server and telecom power supplies
 - SMPS
- Industrial
 - Welding
 - Induction heating
 - Motor drives
- · Battery chargers

| ORDERING INFORMATION | |
|----------------------|----------------|
| Package | TO-220 FULLPAK |
| Lead (Pb)-free | SiHF10N40D-E3 |

| ABSOLUTE MAXIMUM RATINGS (T _C | = 25 °C, unle | ess otherwis | se noted) | | |
|---|-------------------------|-------------------------|-----------------------------------|-------------|------|
| PARAMETER | | SYMBOL | LIMIT | UNIT | |
| Drain-Source Voltage | | | V_{DS} | 400 | |
| Gate-Source Voltage | | | V _{GS} | ± 30 | V |
| Gate-Source Voltage AC (f > 1 Hz) | | | | 30 | |
| Continuous Proin Current (T. – 150 °C) 6 | V _{GS} at 10 V | T _C = 25 °C | 1 | 10 | |
| Continuous Drain Current (T _J = 150 °C) ^e | V _{GS} at 10 V | T _C = 100 °C | I _D | 6 | Α |
| Pulsed Drain Current ^a | | I _{DM} | 23 | | |
| Linear Derating Factor | | | | 0.26 | W/°C |
| Single Pulse Avalanche Energy b | | | E _{AS} | 194 | mJ |
| Maximum Power Dissipation | | | P_{D} | 33 | W |
| Operating Junction and Storage Temperature Range | | | T _J , T _{stg} | -55 to +150 | °C |
| Drain-Source Voltage Slope | $T_{J} = 1$ | 25 °C | dV/dt | 24 | V/ns |
| Reverse Diode dV/dt ^d | | av/at | 0.6 | V/IIS | |
| Soldering Recommendations (Peak temperature) c For 10 s | | 10 s | | 300 | °C |
| Mounting Torque M3 screw | | crew | | 0.6 | Nm |

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. $V_{DD} = 50$ V, starting $T_J = 25$ °C, L = 2.3 mH, $R_g = 25$ Ω , $I_{AS} = 13$ A.
- c. 1.6 mm from case.
- d. $I_{SD} \leq I_{D}$, starting T_{J} = 25 °C.
- e. Limited by maximum junction temperature.



Vishay Siliconix

| THERMAL RESISTANCE RATINGS | | | | |
|----------------------------------|-------------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | R _{thJA} | - | 65 | °C/W |
| Maximum Junction-to-Case (Drain) | R _{thJC} | - | 3.8 | G/VV |

| PARAMETER | SYMBOL | TES | T CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|---|---|------|------|-------|------|
| Static | | | | | • | • | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} : | = 0 V, I _D = 250 μA | 400 | - | - | V |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | Reference | to 25 °C, I _D = 250 μA | - | 0.53 | - | V/°C |
| Gate-Source Threshold Voltage (N) | V _{GS(th)} | V _{DS} = | = V _{GS} , I _D = 250 μA | 3 | - | 5 | V |
| Gate-Source Leakage | I _{GSS} | | V _{GS} = ± 30 V | - | - | ± 100 | nA |
| Zara Cata Valtaga Drain Current | | V _{DS} = | $V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$ | | - | 1 | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 320 \ | V, V _{GS} = 0 V, T _J = 125 °C | - | - | 10 | μA |
| Drain-Source On-State Resistance | R _{DS(on)} | $V_{GS} = 10 \text{ V}$ | $I_D = 5 A$ | - | 0.5 | 0.6 | Ω |
| Forward Transconductance | 9 _{fs} | V _{DS} | $= 50 \text{ V}, I_D = 5 \text{ A}$ | - | 2.7 | - | S |
| Dynamic | | | | | | | |
| Input Capacitance | C_{iss} | | $V_{GS} = 0 V$, | | 526 | - | |
| Output Capacitance | C_{oss} | | $V_{DS} = 100 \text{ V},$ | - | 59 | - | - |
| Reverse Transfer Capacitance | C_{rss} | | f = 1 MHz | - | 9 | - | |
| Effective Output Capacitance, Energy Related ^a | $C_{\text{o(er)}}$ | $V_{GS} = 0 V$, | | - | 66 | - | pF |
| Effective Output Capacitance, Time Related ^b | $C_{o(tr)}$ | V _D | _S = 0 V to 320 V | - | 84 | - | |
| Total Gate Charge | Qg | | | - | 15 | 30 | |
| Gate-Source Charge | Q_{gs} | V _{GS} = 10 V | $I_D = 5 A, V_{DS} = 320 V$ | - | 4 | - | nC |
| Gate-Drain Charge | Q _{gd} | | | - | 7 | - | |
| Turn-On Delay Time | t _{d(on)} | | | - | 12 | 24 | |
| Rise Time | t _r | V _{DD} = | = 400 V, I _D = 10 A, | - | 18 | 36 | no |
| Turn-Off Delay Time | t _{d(off)} | | $V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$ | | 18 | 36 | ns |
| Fall Time | t _f | | | | 14 | 28 | |
| Gate Input Resistance | R _g | f = 1 MHz, open drain | | 0.9 | 1.8 | 3.6 | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | | |
| Continuous Source-Drain Diode Current | I _S | MOSFET sym | MOSFET symbol showing the | | - | 10 | |
| Pulsed Diode Forward Current | I _{SM} | integral revers p - n junction | | - | - | 40 | A |
| Diode Forward Voltage | V _{SD} | T _J = 25 ° | C, I _S = 5 A, V _{GS} = 0 V | - | - | 1.2 | V |
| Reverse Recovery Time | t _{rr} | | | - | 230 | - | ns |
| Reverse Recovery Charge | Q _{rr} | | 5 °C, I _F = I _S = 5 A, | - | 1.6 | - | μC |
| Reverse Recovery Current | I _{RRM} | $dI/dt = 100 \text{ A/}\mu\text{s}^{-1}\text{V}_{R} = 25 \text{ V}$ | | - | 14 | - | A |

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

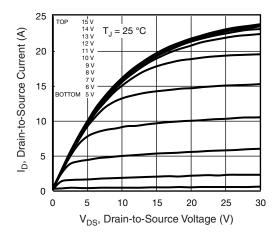


Fig. 1 - Typical Output Characteristics

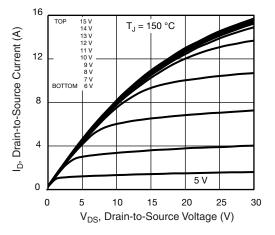


Fig. 2 - Typical Output Characteristics

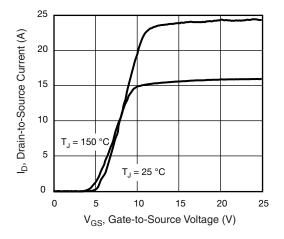


Fig. 3 - Typical Transfer Characteristics

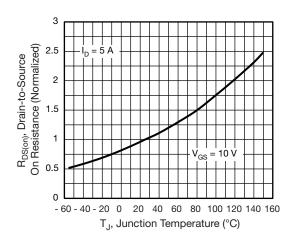


Fig. 4 - Normalized On-Resistance vs. Temperature

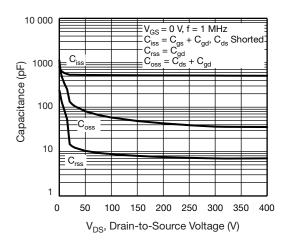


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

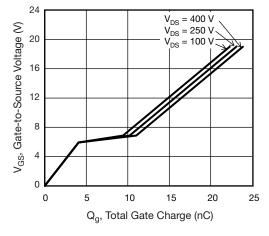


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



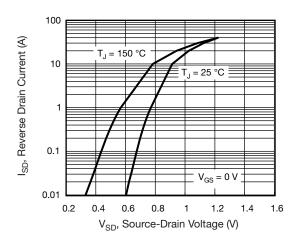


Fig. 7 - Typical Source-Drain Diode Forward Voltage

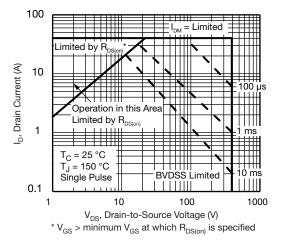


Fig. 8 - Maximum Safe Operating Area

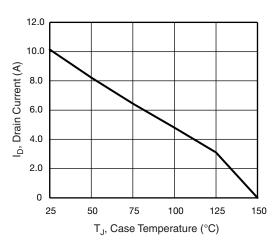


Fig. 9 - Maximum Drain Current vs. Case Temperature

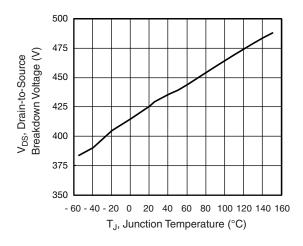


Fig. 10 - Temperature vs. Drain-to-Source Voltage

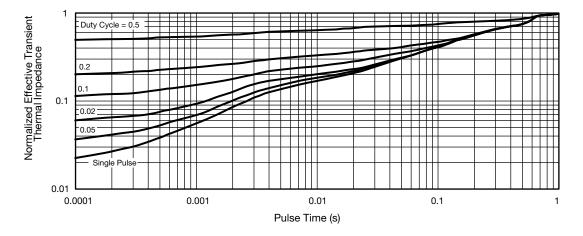


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

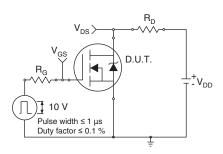


Fig. 12 - Switching Time Test Circuit

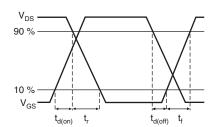


Fig. 13 - Switching Time Waveforms

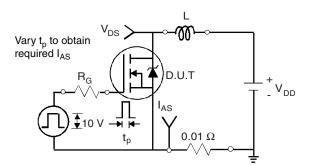


Fig. 14 - Unclamped Inductive Test Circuit

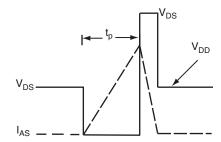


Fig. 15 - Unclamped Inductive Waveforms

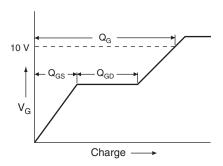


Fig. 16 - Basic Gate Charge Waveform

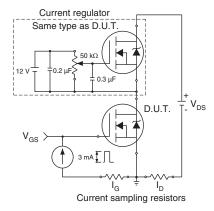
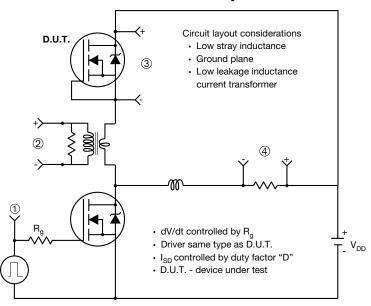


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



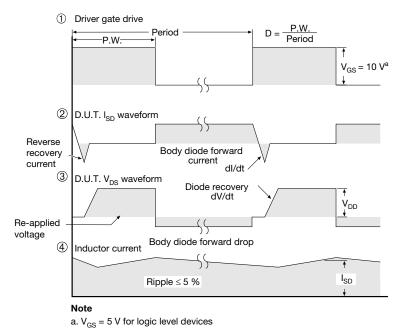


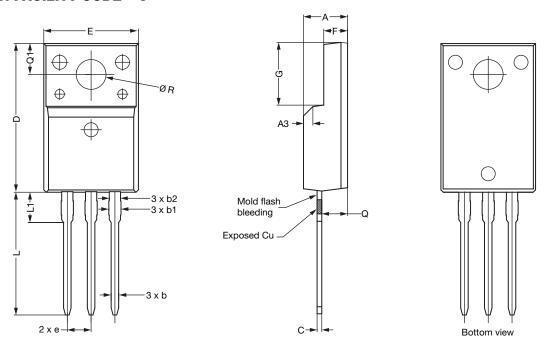
Fig. 18 - For N-Channel

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TO-220 FULLPAK (High Voltage)

OPTION 1: FACILITY CODE = 9

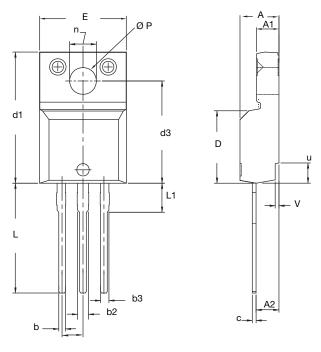


| | | MILLIMETERS | |
|------|-------|-------------|-------|
| DIM. | MIN. | NOM. | MAX. |
| Α | 4.60 | 4.70 | 4.80 |
| b | 0.70 | 0.80 | 0.91 |
| b1 | 1.20 | 1.30 | 1.47 |
| b2 | 1.10 | 1.20 | 1.30 |
| С | 0.45 | 0.50 | 0.63 |
| D | 15.80 | 15.87 | 15.97 |
| е | | 2.54 BSC | |
| E | 10.00 | 10.10 | 10.30 |
| F | 2.44 | 2.54 | 2.64 |
| G | 6.50 | 6.70 | 6.90 |
| L | 12.90 | 13.10 | 13.30 |
| L1 | 3.13 | 3.23 | 3.33 |
| Q | 2.65 | 2.75 | 2.85 |
| Q1 | 3.20 | 3.30 | 3.40 |
| ØR | 3.08 | 3.18 | 3.28 |

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



OPTION 2: FACILITY CODE = Y



| | MILLIMETERS | | MILLI | INCI | HES |
|------|-------------|--------|-----------|-------|-----|
| DIM. | MIN. | MAX. | MIN. | MAX. | |
| Α | 4.570 | 4.830 | 0.180 | 0.190 | |
| A1 | 2.570 | 2.830 | 0.101 | 0.111 | |
| A2 | 2.510 | 2.850 | 0.099 | 0.112 | |
| b | 0.622 | 0.890 | 0.024 | 0.035 | |
| b2 | 1.229 | 1.400 | 0.048 | 0.055 | |
| b3 | 1.229 | 1.400 | 0.048 | 0.055 | |
| С | 0.440 | 0.629 | 0.017 | 0.025 | |
| D | 8.650 | 9.800 | 0.341 | 0.386 | |
| d1 | 15.88 | 16.120 | 0.622 | 0.635 | |
| d3 | 12.300 | 12.920 | 0.484 | 0.509 | |
| Е | 10.360 | 10.630 | 0.408 | 0.419 | |
| е | 2.54 | BSC | 0.100 BSC | | |
| L | 13.200 | 13.730 | 0.520 | 0.541 | |
| L1 | 3.100 | 3.500 | 0.122 | 0.138 | |
| n | 6.050 | 6.150 | 0.238 | 0.242 | |
| ØΡ | 3.050 | 3.450 | 0.120 | 0.136 | |
| u | 2.400 | 2.500 | 0.094 | 0.098 | |
| V | 0.400 | 0.500 | 0.016 | 0.020 | |

ECN: E19-0180-Rev. D, 08-Apr-2019 DWG: 5972

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- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



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Vishay

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